

Abstract

A lead frame and a method of manufacturing thereof

A method of manufacturing a lead frame, comprising the steps of: providing an
5 electrically-conductive base material having first and second planar sides; forming a
patterned conductive layer on the first planar side of the base material; etching the
second planar side of the base material at portions with respect to exposed portions on
the first planar side of the base material comprising the patterned conductive layer, to
form partially-etched portions on the second planar side of the base material; providing
10 a non-conductive filling material over the second planar side of the base material,
wherein the filling material fills spaces inside the partially-etched portions on the second
planar side of the base material to form adjacent portions of the filling material and a
plurality of conductive portions on the second planar side of the base material; and
15 etching the exposed portions of the first planar side of the base material comprising the
patterned conductive layer to form partially-etched portions on the first planar side of the
base material that combine with the partially-etched portions on the second planar side
of the base material to thereby form a plurality of separate conductive regions on the
first planar side of the base material, each conductive region being electrically
20 conductive with at least a respective one of the plurality of conductive portions on the
second planar side of the base material.

[FIG. 2b]